Part Number: **DMN4034SSS**
Weight (mg): 74.674

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Die,Mosfet	Doped silicon	Doped silicon *	7440-21-3	100.00%	1.005	0.751	1000000	10053
SOIC8 leadframe	CDA 194	Cu	7440-50-8	97.40%	52.265	39.029	974000	509063
		Fe	1309-37-1	2.40%			24000	12544
		P	7723-14-0	0.08%			800	418
		Zn	7440-66-6	0.12%			1200	627
	Pure silver	Ag	7440-22-4	100.00%	0.956	0.714	1000000	9562
Bonding wire	1.0mil	Au	7440-57-5	100.00%	0.891	0.665	1000000	8910
Molding compound	EME-G600	Epoxy Resin	------	5.00%	42.129	31.460	50000	21065
		Phenol Resin	------	5.00%			50000	21065
		Bismuth/Bismuth compound	------	0.05%			500	211
		SiO2	60676-86-0	87.45%			874500	368419
		Cresol Novolac	29690-82-2	2.00%			20000	8426
		C	1333-86-4	0.50%			5000	2106
Die attached epoxy	8200TI	Ag	7440-22-4	80.00%	0.477	0.356	800000	3819
		Acrylate resins	Trade secret	20.00%			200000	955
Tin solder	Pure Tin	Sn	7440-31-5	100.00%	2.276	1.699	1000000	22758
					100.00	74.674		1000000

Tolerance ±10%

This data is based on information provided by our suppliers. We believe it to be correct but do not routinely validate it by measurement. It is for guidance only and Diodes Inc. does not guarantee its absolute accuracy or completeness

***** The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of EIA JIG-101, *Material Composition Declaration for Electronic Products*.

This product or product family does not contain any of the following substances except as **CURRENTLY** exempted by ELV II and RoHS and reported above:

Antimony compounds
Asbestos
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including **DecaBDE**
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

This product or product family meet REACH requirements for chemicals designated by the European Chemicals Agency (ECHA) as Substances of Very High Concern (SVHC) appended below:

Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate (DBP)
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Bis(tributyltin)oxide (TBTO)
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate (BBP)
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Alkanes, C10-13, chloro (SCCPs - Short Chain Chlorinated Paraffins)